





#### **40V NPN MEDIUM POWER PLANAR TRANSISTOR IN SOT23**

#### **Features and Benefits**

- BV<sub>CEO</sub> > 40V
- I<sub>C</sub> = 4A Continuous Collector Current
- Low Saturation Voltage V<sub>CE(sat)</sub> < 55mV @ 1A</li>
- $R_{CE(sat)} = 35m\Omega$
- h<sub>FE</sub> characterised up to 10A
- High h<sub>FE</sub> min 300 @ 1A
- 1.25W power dissipation
- 130V forward blocking voltage
- 6V reverse blocking voltage
- Complementary part number ZXTP25040DFH
- "Lead-Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

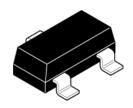
#### **Mechanical Data**

- Case: SOT23
- Case material: Molded Plastic. "Green" Molding Compound (Note 2) UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (Approximate)

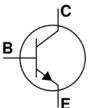
#### **Applications**

- MOSFET gate drivers
- Power switches
- Motor control
- DC fans
- DC-DC converters

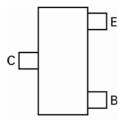
SOT23



Top View



Device Symbol



Top View Pin Configuration

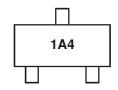
### Ordering Information (Note 3)

Product	Product Marking R		Tape width (mm)	Quantity per reel	
ZXTN25040DFHTA	1A4	7	8	3.000	

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" Policy can be found on our website at https://www.diodes.com/
- 3. Devices with lot number starting from PID0155145 (March 2010) are "Green" products.

### **Marking Information**



1A4 = Product Type Marking Code





### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	$V_{CBO}$	130	V	
Collector-Emitter Voltage (Forward Blockin	V <sub>CEX</sub>	130	V	
Collector-Emitter Voltage		$V_{CEO}$	40	V
Emitter-Collector Voltage (Reverse Blocking)		V <sub>ECO</sub>	6	V
Emitter-Base Voltage		$V_{EBO}$	7	V
Continuous Collector Current	(Note 6)	Ic	4	Α
Peak Pulse Current		Ісм	10	Α
Base Current	I <sub>B</sub>	1	Α	

### Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit		
	(Note 4)		0.73 5.84			
Power Dissipation	(Note 5)	P <sub>D</sub>	1.05 8.4	W		
Linear Derating Factor	(Note 6)	] -	1.25 9.6	mW/°C		
	(Note 7)		1.81 14.5			
	(Note 4)		171			
Thermal Desistance Junation to Ambient	(Note 5)		119	00/14/		
Thermal Resistance, Junction to Ambient	(Note 6)	− R <sub>θJA</sub>	100	°C/W		
	(Note 7)		69			
Thermal Resistance, Junction to Lead (Note 8)		$R_{ heta JL}$	74.95	°C/W		
Operating and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C			

#### Notes:

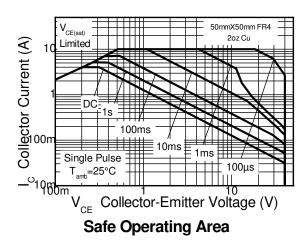
- 4. For a device surface mounted on 15mm X 15mm X 1.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 5. For a device surface mounted on 25mm X 25mm X 1.6mm FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 6. For a device surface mounted on 50mm X 50mm X 1.6mm FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

  7. As note 6 above, measured at t < 5 seconds

  8. Thermal resistance from junction to solder-point (at the end of the collector lead).

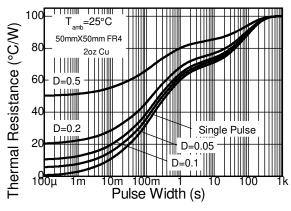


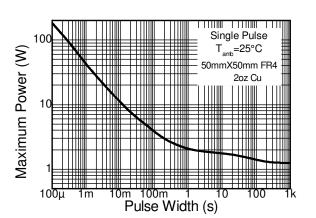
### **Typical Thermal Characteristics**



Tamb=25°C BV(BR)CEX=130V VCE Collector-Emitter Voltage (V)

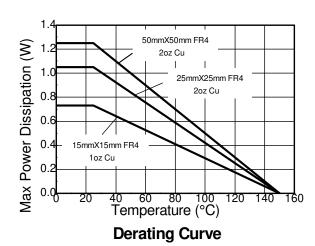






#### **Transient Thermal Impedance**

**Pulse Power Dissipation** 







# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

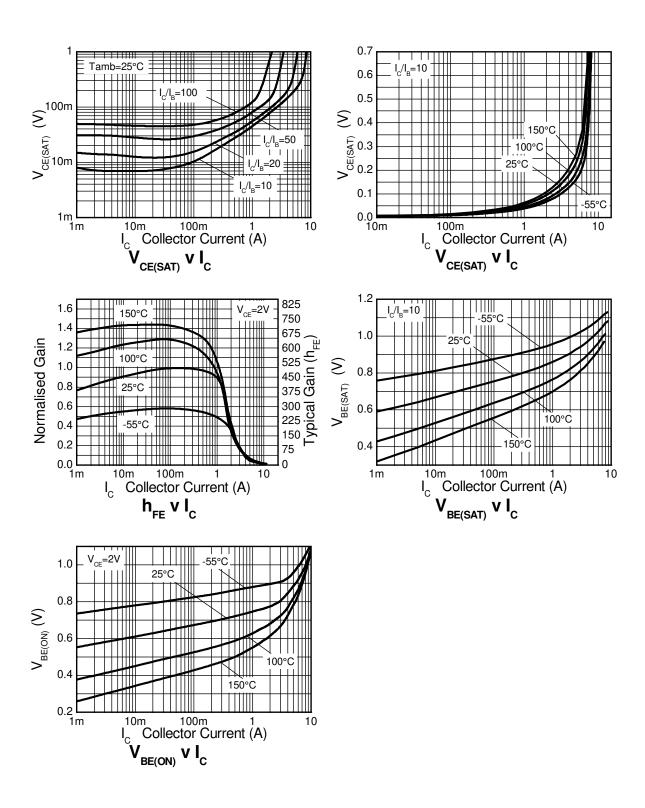
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS				-			
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	130	170	-	V	$I_C = 100\mu A$	
Collector-emitter breakdown voltage (forward blocking)	BV <sub>CEX</sub>	130	170	-	V	$I_{C} = 100 \mu A; R_{BE} < 1 k\Omega \text{ or}$ -1V < $V_{BE} < 0.25 V$	
Collector-Emitter Breakdown Voltage (base open) (Note 9)	BV <sub>CEO</sub>	40	63	-	V	I <sub>C</sub> = 10mA	
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	8.3	-	V	$I_E = 100\mu A$	
Emitter-collector breakdown voltage (reverse blocking)	BV <sub>ECX</sub>	6	7.4	-	V	$I_E = 100 \mu A$ ; $R_{BC} < 1 k \Omega$ or $-0.25 V < V_{BC} < 0.25 V$	
Emitter-collector breakdown voltage (base open)	BV <sub>ECO</sub>	6	7.4	-	V	$I_E = 100 \mu A;$	
Collector-base Cut-off Current	I <sub>CBO</sub>	-	<1 -	50 20	nA μA	V <sub>CB</sub> = 100V V <sub>CB</sub> = 100V, T <sub>A</sub> = 100°C	
Collector-emitter Cut-off Current	I <sub>CEX</sub>	-	-	100	nA	$\begin{split} &V_{CE} = 100V;  R_{BE} < 1k\Omega \text{ or} \\ &-1V < V_{BE} < 0.25V \end{split}$	
Emitter-base Cut-off Current	I <sub>EBO</sub>	-	<1	50	nA	$V_{EB} = 5.6V$	
ON CHARACTERISTICS (Note 9)							
Static Forward Current Transfer Ratio	h <sub>FE</sub>	300 300 30 -	450 450 60 10	900	-	$\begin{split} &I_{C} = 10 \text{mA}, \ V_{CE} = 2 V \\ &I_{C} = 1 \text{A}, \ V_{CE} = 2 V \\ &I_{C} = 4 \text{A}, \ V_{CE} = 2 V \\ &I_{C} = 10 \text{A}, \ V_{CE} = 2 V \end{split}$	
Collector-Emitter Saturation Voltage	VCE(sat)	-	45 120 135 140	55 210 210 190	mV	$I_C = 1A$ , $I_B = 100mA$ $I_C = 1A$ , $I_B = 10mA$ $I_C = 2A$ , $I_B = 40mA$ $I_C = 4A$ , $I_B = 400mA$	
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	-	960	1050	mV	$I_C = 4A, I_B = 400mA$	
Base-Emitter On Voltage	V <sub>BE(on)</sub>	-	840	950	mV	I <sub>C</sub> = 4A, V <sub>CE</sub> = 2V	
SMALL SIGNAL CHARACTERISTICS (Note 9)	` '						
Transition Frequency	f <sub>T</sub>	-	190	-	MHz	$I_C = 50 \text{mA}, V_{CE} = 10 \text{V},$ f = 100 MHz	
Collector Output Capacitance	C <sub>obo</sub>	-	11.7	20	pF	V <sub>CB</sub> = 10V, f = 1MHz	
Delay time	t <sub>d</sub>	-	64	-	ns	101/	
Rise time	t <sub>r</sub>	-	108	-	ns	$V_{CC} = 10V$	
Storage time	t <sub>s</sub>	-	428	-	ns	$I_C = 1A$ ,	
Fall time	t <sub>f</sub>	-	130	-	ns	$I_{B1} = I_{B2} = 10$ mA	

Notes: 9. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s$ . Duty cycle  $\leq 2\%$ 



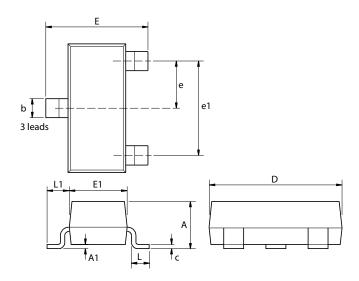


# **Typical Electrical Characteristics**





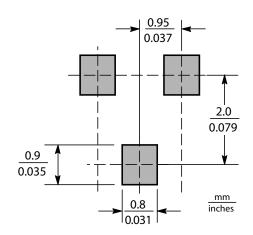
# **Package Outline Dimensions**



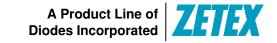
Dim.	Dim. Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
Α	-	1.12	-	0.044	e1	1.90 NOM		0.075 NOM	
A1	0.01	0.10	0.0004	0.004	Е	2.10	2.64	0.083	0.104
b	0.30	0.50	0.012	0.020	E1	1.20	1.40	0.047	0.055
С	0.085	0.20	0.003	0.008	L	0.25	0.60	0.0098	0.0236
D	2.80	3.04	0.110	0.120	L1	0.45	0.62	0.018	0.024
е	0.95	0.95 NOM		0.037 NOM		-	-	-	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

# **Suggested Pad Layout**







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